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(54) **Title:** APPARATUS AND METHOD FOR RECIRCULATING FLUIDS

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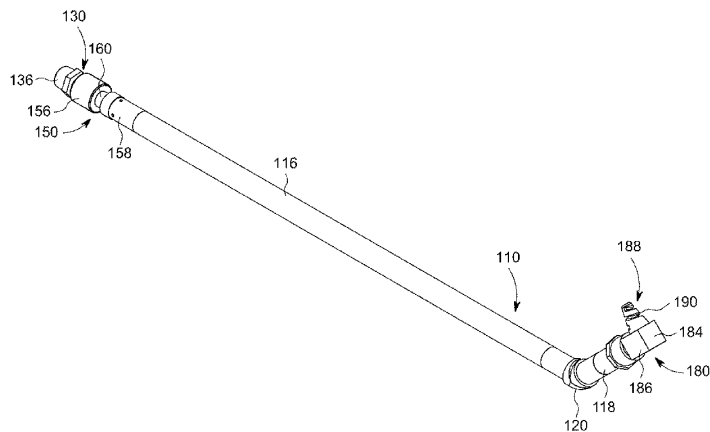


FIG. 1

(57) **Abstract:** An apparatus for recirculating fluids in semiconductor systems. The apparatus including a base portion, an inlet portion coupled to a first end of the base portion, and a nozzle coupled to a second end of the base portion. The nozzle including a helical groove extending from a position near a nozzle base portion to a position near a tip of the nozzle portion. The helical groove extending from an exterior surface through the nozzle portion to an interior surface of the nozzle portion. Methods of using the apparatus in a semiconductor recirculation system are also disclosed.

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